

HD74LS47

BCD-to-Seven-Segment Decoder / Driver (with 15 V Outputs)

REJ03D0410-0301 Rev.3.01 May 10, 2006

HD74LS47 features active-low outputs designed for driving incandescent indicators directly. This device has full ripple-blanking input / output controls and a lamp test. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions. This circuit incorporates automatic leading and / or trailing-edge zero-blanking control (RBI and RBO). Lamp test (LT) of these types may be performed at any time when the BI / RBO node is at a high level. It contains an overriding blanking input (BI) which can be used to control the lamp intensity of pulsing or to inhibit the outputs. Inputs and outputs are entirely compatible for use with TTL or DTL logic outputs.

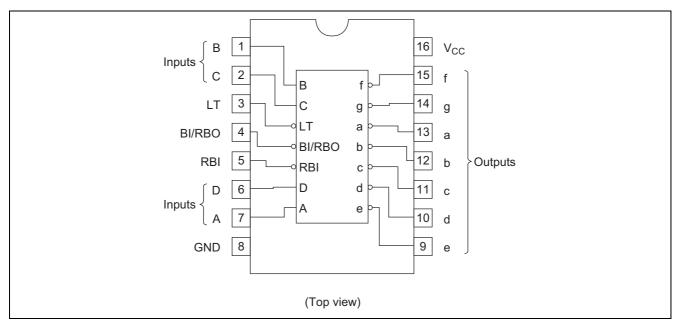
Features

Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS47P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	Р	_
HD74LS47FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



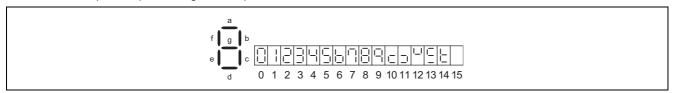
Function Table

Decimal or			Inpu	ıts			BI/			(Output	S			Note
Function	LT	RBI	D	С	В	Α	RBO	а	b	С	d	е	f	g	Note
0	Н	Н	L	L	L	L	Н	ON	ON	ON	ON	ON	ON	OFF	
1	Н	Χ	L	L	Ш	Η	Н	OFF	ON	ON	OFF	OFF	OFF	OFF	
2	Н	Χ	L	L	Ι	L	Н	ON	ON	OFF	ON	ON	OFF	ON	
3	Н	Х	L	L	Н	Н	Н	ON	ON	ON	ON	OFF	OFF	ON	
4	Н	Х	L	Н	L	L	Н	OFF	ON	ON	OFF	OFF	ON	ON	
5	Н	Х	L	Н	L	Н	Н	ON	OFF	ON	ON	OFF	ON	ON	
6	Н	Х	L	Н	Н	L	Н	OFF	OFF	ON	ON	ON	ON	ON	
7	Н	Х	L	Н	Н	Н	Н	ON	ON	ON	OFF	OFF	OFF	OFF	1
8	Н	Х	Н	L	L	L	Н	ON	ON	ON	ON	ON	ON	ON	'
9	Н	Х	Н	L	L	Н	Н	ON	ON	ON	OFF	OFF	ON	ON	
10	Н	Х	Н	L	Н	L	Н	OFF	OFF	OFF	ON	ON	OFF	ON	
11	Н	Х	Н	L	Н	Н	Н	OFF	OFF	ON	ON	OFF	OFF	ON	
12	Н	Х	Н	Н	L	L	Н	OFF	ON	OFF	OFF	OFF	ON	ON	
13	Н	Х	Н	Н	L	Н	Н	ON	OFF	OFF	ON	OFF	ON	ON	
14	Н	Х	Н	Н	Н	L	Н	OFF	OFF	OFF	ON	ON	ON	ON	
15	Н	Х	Н	Н	Н	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	OFF	
BI	Х	Х	Χ	Х	Х	Х	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	2
RBI	Н	L	L	L	L	L	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	3
LT	L	Х	Х	Х	Χ	Х	Н	ON	ON	ON	ON	ON	ON	ON	4

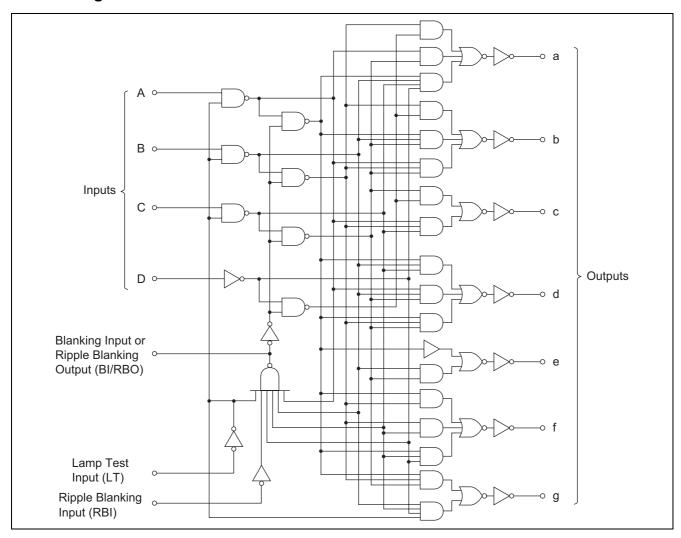
H; high level, L; low level, X, irrelevant

Notes: 1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.

- 2. When a low logic level is applied directly to the blanking input (BI), all segment outputs are off regardless of the level of any other input.
- 3. When ripple-blanking input (RBI) and inputs A, B, C, and D are a low level with the lamp test input high, all segment outputs go off and the ripple-blanking output (RBO) goes to a low level (response condition).
- 4. When a blanking input / ripple blanking output (BI / RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are on.



Block Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V _{CC}	7	V
Input voltage	V _{IN}	7	V
Output current (tw ≤ 1ms,duty cycle ≤ 10%)	I _{O(peak)}	200	mA
Output current (off)	I _{O(off)}	1	mA
Power dissipation	P _T	400	mW
Operating temperature	Tupr	-20 to +75	°C
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{CC}	4.75	5.00	5.25	V
Output voltage (off)	$V_{O(off)}$	_	_	15	V
Input current (on)	I _{O(on)}	_	_	24	mA
Output current	I _{OH}	_	_	- 50	μΑ
Output current	I _{OL}	_	_	3.2	mA
Operating temperature	Topr	-20	25	75	°C

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$

Item		Symbol	min.	typ.*	max.	Unit	Co	ondition	
Input voltage		V_{IH}	2.0		_	V			
Input voltage		V_{IL}	_	_	0.8	V			
	DI / DDO	V _{OH}	2.4	_	_	V	$V_{CC} = 4.75 \text{ V}, \text{ V}_{IH}$ = -50 μ A	$_{H} = 2 \text{ V}, \text{ V}_{IL} = 0.8 \text{ V}, \text{ I}_{OH}$	
Output	BI / RBO	V _{OL}			0.4	V	$I_{OL} = 1.6 \text{ mA}$	$V_{CC} = 4.75 \text{ V},$	
voltage		V OL			0.5	V	$I_{OL} = 3.2 \text{ mA}$	$V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}$	
	a to d	Vac			0.4	V	$I_{O(on)} = 12 \text{ mA}$	$V_{CC} = 4.75 \text{ V},$	
	a to g	$V_{O(on)}$			0.5	V	$I_{O(on)} = 24 \text{ mA}$	$V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}$	
Output current	a to g	I _{O(off)}		1	250	μΑ	$V_{CC} = 5.25 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, V_{O(off)} = 15 \text{ V}$		
		I _{IH}	_	_	20	μΑ	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$		
Input current	All input except BI / RBO	I _{IL}			-0.4	mA	V _{CC} = 5.25 V, V _I	= 0.4 V	
	BI / RBO		_	_	-1.2	mA			
		I _I	_	_	0.1	mA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I}$	= 7 V	
Short-circuit output current	BI / RBO	I _{OS}	-0.3		-2	mA	V _{CC} = 5.25 V		
Supply current**		I _{CC}		7	13	mA	V _{CC} = 5.25 V		
Input clamp vol	tage	V_{IK}	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN}$	= -18 mA	

Notes: * $V_{CC} = 5 \text{ V}$, $Ta = 25^{\circ}\text{C}$

Switching Characteristics

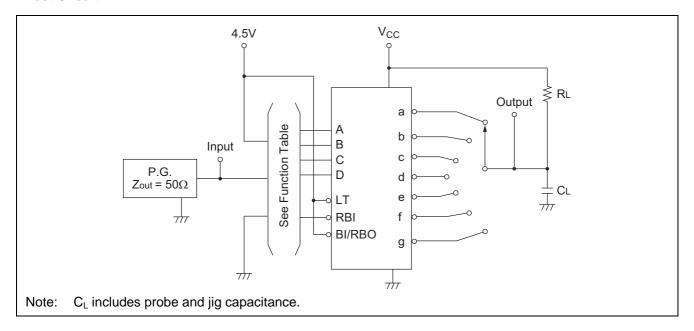
 $(V_{CC} = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C})$

Item	Symbol	Input	min.	typ.	max.	Unit	Condition		
Turn-on time	+	Α		_	100	ns			
Turr-on time	Lon	RBI	_	_	100	115	$C_L = 15 \text{ pF}, R_L = 665 \Omega$		
Turn-off time	+	Α	_	_	100	ns	$C_{L} = 15 \text{ pr}, K_{L} = 005 22$		
	t _{off}	RBI		_	100	115			

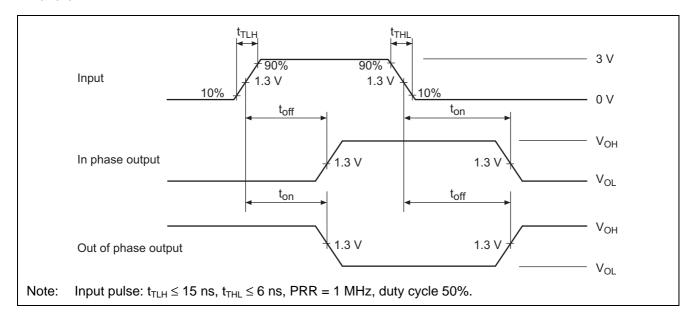
^{**} I_{CC} is measured with all outputs open and inputs at 4.5 V.

Testing Method

Test Circuit



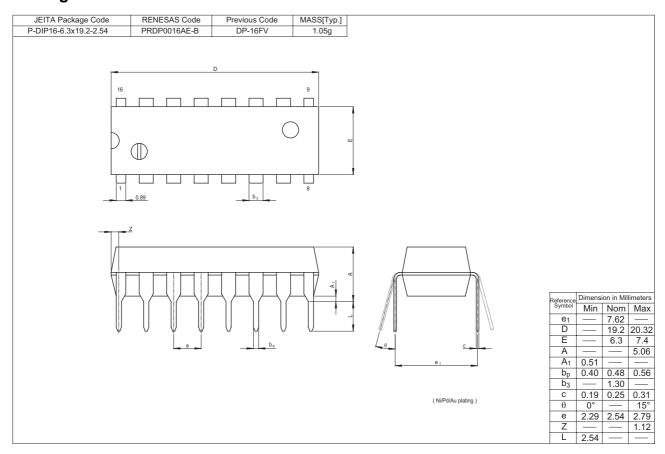
Waveform

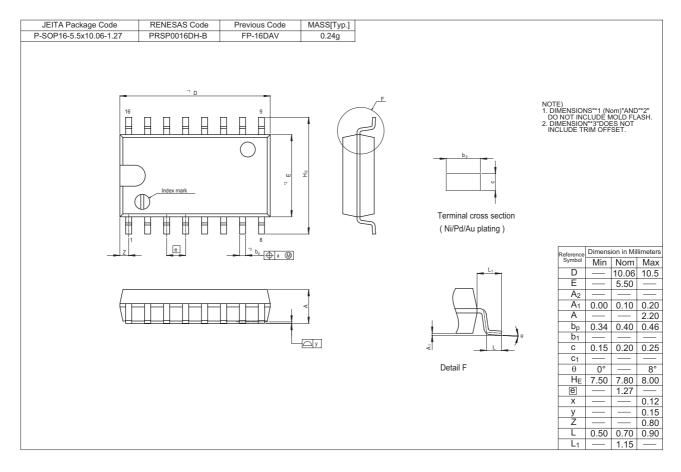


Testing Table

Item			Inputs			Outputs						
Item	RBI	D	С	В	Α	а	b	С	d	е	f	g
	4.5 V	GND	GND	GND	IN	OUT	_	_	OUT	OUT	OUT	_
t _{on}	4.5 V	GND	GND	4.5 V	IN	_	_	OUT	_	OUT	_	_
t _{off}	4.5 V	GND	4.5 V	4.5 V	IN	OUT	OUT	_	OUT	OUT	OUT	OUT
	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	OUT	OUT	_

Package Dimensions





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